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- (54) Title: EXTRUSION PROCESS FOR MANUFACTURING A Z-DIRECTED COMPONENT FOR A PRINTED CIRCUIT BOARD

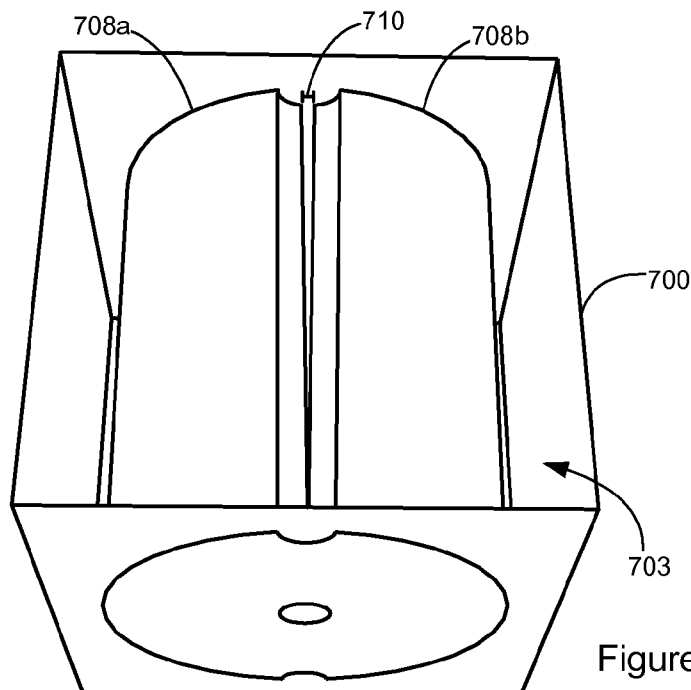


Figure 15A

(57) Abstract: A method for manufacturing a Z-directed component for insertion into a mounting hole in a printed circuit board according to one example embodiment includes extruding a substrate material according to the shape of the Z-directed component. A conductive material is then selectively applied to the extruded substrate material and the Z-directed component is formed from the extruded substrate material.



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